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电子塑封模

塑料封装是生产塑封晶体管的关键工艺装备。各技术先进国家已普遍使用。

本成果研制的电子塑料封装模是一种多型腔,高精度的大型模具。生产效率高、工艺简便,可大量连续生产、成本低,器件质量高、刚度大,模具承载部位在空腔处有刚度较大的支柱,且分布密度较大,模具型腔均设有跑气孔,主流道有闸流装置,上下模有加热线和隔热板;同时带有金属件夹板两付及易损件六件。精度高,基体件、型腔件均经精加工或超精加工,型腔粗糙度为 0.05,模盒组件不等高,误差小于 0.002,定模板工作面的平面度小于 0.003,上下模型腔位错小于 0.015。全模型结构紧凑可靠,承载 50 t 合模压力不变形,塑封的产品无宏观错位,金属件无损伤、无漏胶、无跑胶、毛刺厚度小于 0.01 mm,外形整齐、光亮、美观、尺寸准确;由于定位准确,精度高,并备有金属夹板,装卸模省事,操作简便,生产可连续进行,效率较高;结构简单,并备有易损件,保养维修方便。

300 腔塑封模各项技术指标先进,达到国外同类产品水平。采用本成果国产塑封模可大量节省外汇。本设备经晶体管厂生产使用,生产的各种型号塑封晶体三极管,产品外观光亮、无沙眼、凹坑、水迹等常见封装毛病,外形质量符合 IEC 国际标准,曾获国家银质奖。研制的 400 腔塑封模,将使晶体管塑封效率进一步提高。

· 李连清 ·